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Ventec International Group presents cutting edge innovations and high-performance formulas at IPC APEX EXPO 2025.

March 18-20 – Booth 4116, Anaheim Convention Center, California

- **New VT-47LT IPC4101 /126 low CTE pre-preg for high reliability HDI**
- **Hi Print SD-11 – 3-Color IJSM Printer for the additive soldermask process**
- **Pro-Bond and Thermal-Bond non-reinforced Bond-ply dielectrics for high-speed signal integrity or thermal conductivity**

Ventec International Group is presenting new substrate materials and proven formulas for high-performance PCBs at IPC APEX Expo 2025, alongside the latest advances in manufacturing equipment from Ventec Giga Solutions.

Expo visitors can see it all at booth 4116 and find out from Ventec specialists how the company's technical expertise and supply-chain integrity keep high-quality production moving.

New at APEX this year, Ventec's VT-47LT IPC4101 /126 advanced pre-preg ensures high-reliability performance for boards with high density interconnect (HDI). Its best-in-class z-axis coefficient of thermal expansion (CTE) minimizes stress on microvias structures, has exceptional thermal resilience and enhances reliability. As a cutting-edge IPC 4101/126 pre-preg, VT-47LT saves time-consuming and expensive requalification of alternative IPC4101 grades to deliver a competitive advantage and faster implementation.

Headlining for Ventec Giga Solutions, the Hi Print SD-11 is a 10-head, 3-color full-coverage soldermask printer that showcases the latest advancements and applications of inkjet printing for PCB production. "Inkjet soldermask technology is becoming increasingly important within the PCB manufacturing community," comments Leigh Allinson, Ventec Giga Solutions Commercial Director. Leigh will be at the booth throughout the expo to discuss the SD-11 and the fastest way for fabricators to start taking advantage of its capabilities on their factory floor. Also featured will be equipment for legend printing and additional roll-to-roll flex printing options.

There is plenty more to see at booth 4116, including Ventec's Bondply dielectrics -- Pro-Bond and Thermal-Bond -- which are formulated for high-speed signal integrity, low-loss performance, and thermal management in multilayer PCB stack-ups. Ideal for cutting-edge AI computing and networking applications, these materials are chosen anywhere optimal electrical performance or heat dissipation is essential, including high-layer-count multilayers, high-performance motherboards, server backplanes, and cellular network power amplifiers.

With ultra-low dielectric constant (Dk) and dissipation factor (Df), Pro-Bond materials are available in multiple thicknesses, with resin-coated film (RCF) or resin-coated copper (RCC) variants, and electrical values as low as Dk 2.85 and Df 0.0016, Ventec Pro-Bond brings design solution to high performance, high density interconnect PCBs. RCC Bondply is an unreinforced adhesive system coated onto ultra-thin copper foil (1.5-5.0µm supported on an 18µm carrier foil), ideal for high-performance and high-reliability multilayer PCB stack-ups. Also targeting high-performance and high-reliability multilayer PCB stack-ups, RCF Bondply offers the choice of an unreinforced adhesive system coated onto PET or PI film.

The Thermal-Bond family is a range of thermally conductive resin coated films (RCF) that has high Tg (180-210°C), high MOT (150°C) and thermal conductivity as high as 9.0W/m-K in Thermal Bond 7.0F. RCC, ideal for ensuring optimized heat management of high-density, high-frequency or high-powered PCBs, and to manage heat dissipation from embedded components, or metal in board (MiB) technology.

The Pro-Bond and Thermal Bond families of products are natural evolutions for Ventec, utilizing its proprietary film coating technology and expertise, initially developed for producing non-reinforced dielectrics for its best-in-class Tec-Thermal Insulated Metal Substrate (IMS) product range.

Join Ventec at booth 4116, IPC APEX EXPO, in the Anaheim Convention Center, to see the latest innovations in specialty substrate materials, process consumables, and one-stop-shop fabrication services from Ventec Giga Solutions.

The Ventec team looks forward to welcoming you!

Further information about Ventec's solutions and the company's wide variety of products is available at www.venteclaminates.com

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About Ventec International Group

Ventec International Group Co., Ltd. is a Taiwan Stock Exchange listed (TWSE:6672.TT) global supplier of advanced base materials for the PCB industry worldwide. Ventec's range of laminates & prepregs include signal integrity/high-speed digital, RF/Analog & high-performance IMS material technology, and an advanced range of thermal management solutions designed for specialized use in industries including automotive, communication, aerospace, and defense. Ventec also provides value-added one-stop shop services to support PCB manufacturing and distributes a range of third-party materials and automated production equipment that complement its core product offering. Operating its own fully controlled and managed global supply chain and worldwide sales and technical support network, Ventec has manufacturing, and distribution facilities located throughout Asia, Europe, and the US, certified to AS9100 Revision D, IATF 16949:2016 and ISO 9001:2015. For more information, visit www.venteclaminates.com

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